

Appl. No. 10/516,713; Docket No. DE02 0137 US  
Amdt. dated November 15, 2006  
Response to Final Office Action dated October 11, 2006

### REMARKS/ARGUMENTS

Claims 1-10 remain pending in the application.

Claim 1 has been amended to further clarify the feature of "at least one component integrated in the silicon substrate. . ." by adding the word "*planarly*" in the claim language.

Claim 7 has been amended to further clarify the feature, at least one component, having at least one slightly doped zone laterally situated between a first highly doped zone and a second highly doped zone, integrated in the silicon substrate. . ." by adding the words "is planarly."

Claim 10 has been amended clean up the language to better clarify the claimed features.

These changes are supported in the Specification and contain no new matter.

Claims 1-10 are rejected under 35 U.S.C. §102(b) as being anticipated by *Adan* (5,198,379).

Applicants respectfully assert that the claims, as amended are not anticipated by *Adan*. The Office Action Figure 1 structure of alleged "component (S, 3A, D)" depicted, is not planar, whereas Applicants' Fig. 1 structure "component 30" is planar.

In view of the foregoing changes, Applicants respectfully request that the rejections under 35 USC 102(b) be withdrawn and these minor amendments be entered.

Applicants believe they have addressed all of the Examiner's concerns. Therefore, the claims are now allowable. A timely Notice of Allowance is earnestly solicited.

Please charge any fees other than the issue fee and credit any overpayments to Deposit Account 50-4019.

Respectfully submitted,

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